



Sir:

Transmitted herewith for filing is the Patent Application of:

Inventor: **AN-CHUN TU, CHEN-MING HUANG**

For: **METHOD FOR IMPROVING INTERLEVEL DIELECTRIC GAP FILLING OVER SEMICONDUCTOR STRUCTURES**
HAVING HIGH ASPECT RATIOS

Enclosed are:

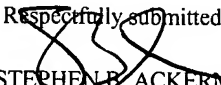
- ☒ **2** sheets of drawing(s) - formal.
- ☒ An assignment of the invention to **Taiwan Semiconductor Manufacturing Co.**
- ☐ An associate power of attorney ☐ Applicant claims small entity status
- ☐ Request & Certification under 35 USC 122(b)(2)(b)(i)

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	OTHER THAN A SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$ 770.
TOTAL CLAIMS	26 -20=	6	x 18 =	\$ 108.
INDEP CLAIMS	2 -3=	0	x 86 =	\$ 0.
SUB TOTAL				\$ 878.
ASSIGNMENT				\$40.
TOTAL				\$ 918.

- ☒ Please charge my Deposit Account No. 19-0033 in the amount of **\$ 918**. A duplicate copy of this sheet is enclosed.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-0033. A duplicate copy of this sheet is enclosed.
- ☒ Any additional filing fees required under 37 CFR §1.16.
- ☒ Any patent application processing fees under 37 CFR §1.17.

Respectfully submitted,

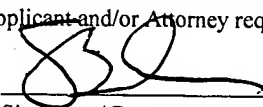

STEPHEN R. ACKERMAN, REG. NO. 37,761

EXPRESS MAIL CERTIFICATE

Express Mail No. **EV313927335US**

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Alexandria, VA, 22313-1450. Applicant and/or Attorney requests the date of deposit as the Filing Date.

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